ABSTRACT

METHOD AND APPARATUS FOR STICKING A FILM TO A LEAD FRAME

An apparatus for sticking a film to a lead frame has a punch moving up and down for punching a film, a die for placing the film to be punched, and a heating plate for heating a lead frame. A punched film with a predetermined shape is applied on the lead frame and thermally compressed and adhesively attached on a lead portion of the lead frame. The die is additionally provided with a buffer layer on the top plane of the die for relaxing compressing stress but increasing tensile stress put to the film at the punching step so that a punched film is prevented from producing cracks on the cutting end thereof.